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2. (Amended) The semiconductor device according to claim 1, wherein a plurality of semiconductor chips are mounted to an outer circumferential surface of said substrate a predetermined distance apart from each other in an outer circumferential direction of said substrate.

3. (Amended) The semiconductor device according to claim 1, wherein a plurality of semiconductor chips are mounted to an outer circumferential surface of said substrate a predetermined distance apart from each other in a longitudinal direction of said substrate.

4. (Amended) The semiconductor device according to claim 1, wherein said semiconductor chip is arranged to cover an entire outer circumferential surface of said substrate.

5. (Amended) The semiconductor device according to claim 1, wherein said semiconductor chip is arranged on an inner circumferential surface of said substrate.

6. (Amended) The semiconductor device according to claim 1, wherein a plurality of semiconductor chips are arranged on an inner circumferential surface of said substrate a predetermined distance apart from each other in an inner circumferential direction of the substrate.

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7. (Amended) The semiconductor device according to claim 1, wherein a plurality of semiconductor chips are arranged on an inner circumferential surface of said substrate a predetermined distance apart from each other in a longitudinal direction of the substrate.

8. (Amended) The semiconductor device according to claim 1, wherein said semiconductor chip is arranged over an entire inner circumferential surface of said substrate.

9. (Amended) The semiconductor device according to claim 1, wherein said semiconductor chips are arranged on both an outer circumferential surface and an inner circumferential surface of said substrate.

10. (Amended) The semiconductor device according to claim 1, wherein an outer circumferential surface of said substrate is sealed with a resin layer.

12. (Amended) The semiconductor device according to claim 1, wherein a plurality of terminals for connection are arranged in one edge portion in a longitudinal direction of said cylindrical substrate, and said terminals are electrically connected to said semiconductor chip.

13. (Amended) A semiconductor device, comprising:  
a cylindrical substrate having wirings formed thereon; and

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at least one stacked body mounted on a circumferential surface of said substrate, said stacked body including a plurality of semiconductor chips stacked one upon the other and being bent along the surface of said substrate, wherein each of said semiconductor chips has bumps, and the bumps formed on one of said semiconductor chips are connected to said wirings.

14. (Amended) The semiconductor device according to claim 13, wherein a plurality of said stacked bodies are mounted to an outer circumferential surface of said substrate a predetermined distance apart from each other in an outer circumferential direction of said substrate.

15. (Amended) The semiconductor device according to claim 13, wherein a plurality of said stacked bodies are arranged a predetermined distance apart from each other in a longitudinal direction of said substrate.

16. (Amended) The semiconductor device according to claim 13, wherein said stacked body is arranged to cover an entire outer circumferential surface of said substrate.

17. (Amended) The semiconductor device according to claim 13, wherein said stacked body is arranged on an inner circumferential surface of said substrate.

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18. (Amended) The semiconductor device according to claim 13, wherein a plurality of stacked bodies are arranged on an inner circumferential surface of said substrate a predetermined distance apart from each other in an inner circumferential direction of the substrate.

*Cmt*  
*Q2*  
19. (Amended) The semiconductor device according to claim 13, wherein a plurality of stacked bodies are arranged on an inner circumferential surface of said substrate a predetermined distance apart from each other in a longitudinal direction of the substrate.

20. (Amended) The semiconductor device according to claim 13, wherein said stacked body is arranged over an entire inner circumferential surface of said substrate.

21. (Amended) The semiconductor device according to claim 13, wherein said stacked bodies are arranged on both an outer circumferential surface and an inner circumferential surface of said substrate.

22. (Amended) The semiconductor device according to claim 13, wherein an outer circumferential surface of said substrate is sealed with a resin layer.

23. (Amended) The semiconductor device according to claim 13, wherein a plurality of terminals for connection are arranged in one edge portion in a longitudinal

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direction of said cylindrical substrate, and said terminals are electrically connected to said semiconductor chip.

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25. (Amended) A method of manufacturing a semiconductor device, comprising:  
bending at least one semiconductor chip; and  
mounting the bent semiconductor chip on at least one region of the surface of a cylindrical substrate,  
wherein said semiconductor chip is held by a holder having a curved surface in said bending step.

26. (Amended) A method of manufacturing a semiconductor device, comprising:  
mounting at least one semiconductor chip having bumps on at least a region of a surface of a flexible substrate; and  
bending said substrate into a cylindrical form.

#### REMARKS

By the present Amendment, Applicant cancels claim 24 without prejudice or disclaimer of the subject matter thereof; amends claims 1, 13, and 26 to more appropriately define the invention; amends claims 2-10, 12, and 14-23 to improve form; and rewrites claim 25 in independent form. Claims 1-23, 25, and 26 are pending.

In the Office Action, the Examiner rejected claims 1-23 under 35 U.S.C. § 112, second paragraph, as being indefinite; rejected claims 1-11, 13, 16, 17, 20, 24, and 26 under 35 U.S.C. § 102(b) as anticipated by Sharp, JP 9-107129; and rejected claims 1, 12, 13, 14, 18, 19, and 21-23 under 35 U.S.C. § 102(b) as anticipated by Buck, U.S.

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